

Appln No. 09/693,484
Amdt. Dated November 12, 2000
Reply to Office action of September 17, 2003

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Amend the claim set, replacing all prior versions, without prejudice or disclaimer of the subject matter thereof, as detailed in the following complete listing of all claims:

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1. (Currently amended) A method of manufacturing an integrated circuit carrier (10), the method including the steps of
providing a substrate (46);
demarcating at least one receiving zone (12) for an integrated circuit (14) on the substrate (46) and a plurality of island-defining portions (16) arranged about said at least one receiving zone (12); and
creating one or more a-serpentine members (22) between neighboring island-defining portions (16) by removing material from the substrate (46), thereby reducing thermal strains involving the said island-defining portions (16).
 2. (Currently amended) The method of claim 1 which includes forming electrical contacts (42) in said at least one receiving zone (12) and forming an electrical terminal (18) in each island-defining portion (16), each electrical terminal (18) being electrically connected via a track (52) of a circuitry layer (48) to one of the electrical contacts (42).
 3. (Currently amended) The method of claim 2 which includes forming the circuitry layer (48) on a surface of the substrate (46) by depositing a metal layer on the substrate (46).
 4. (Cancelled)
 5. (Cancelled)
 6. (Currently amended) The method of claim 1 which includes creating the one or more serpentine members (22) ~~rigidity-reducing arrangements~~ by etching through the substrate (46).

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7. (Currently amended) The method of claim 1 which includes forming the substrate (46) from a wafer of undoped silicon having an insulating layer (54).
8. (Currently amended) The method of claim 1 which includes demarcating said at least one receiving zone (12) by forming a recess in the substrate (46).
9. (Currently amended) The method of claim 8 which includes forming the recess by etching the substrate (46).
10. (Cancelled)
11. (Cancelled)
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